



# Introduction of Asphase-II Global Trigge and Contractions of the second states of the second



# Outline



- Brief introduction on LHC and ATLAS
- Brief introduction on Trigger concept
- ATLAS Global Trigger for Phase-II Upgrade
- Global Common Module (GCM) design
- Summary

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### Large Hardon Collider

- Circumference ~27km
- Nominal energy, protons 7 Tev, 99.9999991% of *c*
- Magnetic dipole field 8.3T, 100,000 times of earth's









### A Toroidal LHC ApparatuS

- ~180 institutes, >3000 authors
- Total detector channels ~100,000,000







• Total data volume generated by ATLAS

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- Collision rate 40MHz x 100 million channels ~ 4x10<sup>15</sup> bytes/s
- Trigger concept
  - The role of the trigger is to select bunch collisions containing potential interesting physics
  - What is "interesting"?
    - Define what is signal and what is background
  - Which is the final affordable rate of the DAQ system?
    - Define the maximum allowed rate







# Multi-level trigger concept

- Adopted in large experiments, successively more complex decisions are made on successively lower data rates
  - First level with short latency, working at higher rates
  - Higher levels apply further rejection power, with longer latency (more complex algorithms)



Fine Complex Slow

# **Original ATLAS TDAQ Architecture**



• Level 1 trigger

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 Rapid rejection of high-rate backgrounds

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- Fast custom electronics
  - Real-time @40MHz
- Coarse calorimeter info
- High lever trigger
  - Event selection
  - Software running on computer farm
  - Access to full event data
    - Full granularity
    - Full precision





### Very successful



- Higgs boson discovery 2012
  - ATLAS together with CMS

Higgs  $\rightarrow$  2mu2e



# The Nobel Prize in Physics 2013



Photo: A. Mahmoud François Englert Prize share: 1/2



Photo: A. Mahmoud Peter W. Higgs Prize share: 1/2





### LHC Luminosity profile and pileup



μ=20 10/24/2024

µ=65 W. Qian - CEPC Workshop

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# ATLAS TDAQ Phase-II Architecture

• LO Trigger

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- Real-time
  - 10 µs latency
  - 1 MHz trigger rate
- LOCalo, LOMuon, CTP
- Global Trigger
  - Running complex full event algorithms inside FPGA at real time

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- E.g. TopoCluster algorithm
- Similar to phase-I offline algorithms running on PC farm









# Global Trigger system overview

- Maximize physics potential by concentrating full event data onto single processing unit
  - Inputs from LAr, Tile, L0Calo, L0Muon at 40 MHz

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- ~ 50 Tb/s into Global Trigger
- Data aggregation to single node with time multiplexing
- Object-level and event-level reconstruction and analysis
- Outputs to Central Trigger Processor for final decision
- Readout on L0 Accept to FELIX



- Different functions implemented in firmware
  - Common hardware platform
    - The Global Common Module



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# **Global Trigger system realization**

- Three-layer system with synchronous interface to rest of ATLAS
  - Nominal 49 node MUX layer
    - captures incoming data from Calorimeters, LOCalo and MuCTPi every BC and streams consecutive events to Global Event Processors in turn
  - Nominal 49 node GEP layer
    - each node receives a new event every 49 BC, performs trigger algorithms, streams results to gCTPi interface
  - Single node gCTPi interface
    - receives list of trigger items from Global Event Processors and sends results to CTP every BC with fixed latency
  - Interconnected by full mesh optical fibre exchange



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# GCM prototype v3

• Main Features

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- ATCA form factor
- AMD/Xilinx Versal Adaptive SoCs
  - 1 versal premium VP1802 for MUX node
  - 1 versal premium VP1802 for GEP/gCTPi node
- Samtec Firefly 25Gx12ch optical modules

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- 8 for GEP/gCTPi node
- 12 for MUX node
- 240 optical links in total
- Power design capacity 540W
  - 1 PIM4328/ 1 BMR458 (-48V/12V)
  - 7 LTM4681/1 LTM4638 (POL)
- Clock chips
  - 2 Si5395A
- 26-layer PCB with backdrill and via-in-pad technology
- Ultralow loss PCB material EM890K





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AMDE

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### VP1802 FPGA



#### • The top-of-the-range AMD/Xilinx versal premium

		VP1002	VP1052	VP1102	VP1202	VP1402	VP1502	VP2502	VP1552	VP1702	VP1802			
	System Logic Cells (K)	833	1,186	1,575	1,969	2,233	3,763	3,738	3,837	5,558	7,352			
Adaptable Engines	LUTs	380,800	542,080	719,872	900,224	1,020,928	1,720,448	1,708,672	1,753,984	2,540,672	3,360,896			
	NoC Master / NoC Slave Ports	22	22	30	28	42	52	52	52	76	100			
	Super Logic Regions (SLRs) <sup>(1)</sup>	-	-	-	-	-	2	2	2	3	4			
	Distributed RAM (Mb)	12	17	22	27	31	53	52	54	78	103			
	Block RAM (Mb)	19	26	49	47	70	89	89	89	132	174			
	UltraRAM (Mb)	97	138	127	190	181	366	366	366	541	717			
Memory	Multiport RAM (Mb)	80	80	-	-	-	-	-	-	-	-			
Wiemory	Total PL Memory (Mb)	208	261	198	264	282	508	507	509	751	994			
	DDR Memory Controllers	2	2	3	4	3	4	4	4	4	4			
	DDR Bus Width	128	128	192	256	192	256	256	256	256	256			
Intelligent	DSP Engines	1,140	1,572	1,904	3,984	2,672	7,440	7,392	7,392	10,896	14,352			
	AI Engines Tiles	-	-	-	-	-	-	472	-	-	-			
Lingines	AI Engine Data Memory (Mb)	-	-	-	-	-	-	118	-	-	-			
	APU	Dual-core Arm <sup>®</sup> Cortex <sup>®</sup> -A72, 48KB/32KB L1 Cache w/ parity & ECC; 1MB L2 Cache w/ ECC												
Scalar	RPU	Dual-core Arm Cortex-R5F, 32KB/32KB L1 Cache, and 256KB TCM w/												
Engines	Memory	256KB On-Chip Memory w/ECC												
	Connectivity		Ethernet (x2); UART (x2); CAN-FD (x2); USB 2.0 (x1); SPI (x2); I2C (x2)											
Corial	GTY Transceivers (32.75Gb/s)	20	20	-	-	-	-	-	-	-	-			
Serial	GTYP Transceivers (32.75Gb/s)	-	-	8	28 <sup>(2)</sup>	8	28(2)	28 <sup>(2)</sup>	68 <sup>(2)</sup>	28 <sup>(2)</sup>	28(2)			
Transceivers	GTM Transceivers (58G (112G))	24 (12)	48 (24)	64 (32)	20 (10)	96 (64) <sup>(3)</sup>	60 (30)	60 (30)	20 (10)	100 (50)	140 (70)			
	PCIe <sup>®</sup> w/DMA & CCIX (CPM4)	2 x Gen4x4	2 x Gen4x4	-	-	-	-	-	-	-	-			
	PCIe w/DMA & CCIX (CPM5)	-	-	-	2 x Gen5x8	-	2 x Gen5x8	2 x Gen5x8	2 x Gen5x8	2 x Gen5x8	2 x Gen5x8			
Integrated	PCI Express	1 x Gen4x8	1 x Gen4x8	2 x Gen5x4	2 x Gen5x4	2 x Gen5x4	2 x Gen5x4	2 x Gen5x4	8 x Gen5x4	2 x Gen5x4	2 x Gen5x4			
	100G Multirate Ethernet MAC	3	5	6	2	6	4	4	4	6	8			
Protocorip	600G Ethernet MAC	2	3	7	1	11	3	3	1	5	7			
	600G Interlaken	1	2	0	0	0	1	1	0	2	3			
	400G High-Speed Crypto Engine	1	1	3	1	4	2	2	2	3	4			

### Power Design

- Worst-case scenario (540W)
  - FPGA ~ 200 W each
  - FireFly ~ 100 W (for 20 modules)
  - Misc ~40 W
- 10 POL DC-DC for ~20 power rails
  - 7 LTM4681
  - 1 LTM4638
  - 2 TPS74801
  - 1 TPS51200
- Independent and symmetric power solution for MUX and GEP
- Two ADM1066 for power sequencing







# PCB technology

- Material: EM890K, Halogen free. •
- Total thickness 2.65mm ± 0.2 mm, milled down on bottom edge
- **5 Backdrill** (stub less than 8 mil):
  - L26 L23, DO NOT BREAK L22
  - L26 L21, DO NOT BREAK L20
  - L26 L19, DO NOT BREAK L18
  - L26 L17, DO NOT BREAK L16
  - L26 L12, DO NOT BREAK L11
- Minimum via for non-backdrill: 8 mil hole / 18 mil pad ٠
- Minimum via for backdrill: 8 mil hole /22mil pad ٠
- **IPC Class II** ٠

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Impedance tolerance ± 10% for 50/93/100 ohm ٠

	ST	ACK UP DETAILS - 26 LAYERS [NOT TO SCALE]	
SOLDERMASK		TODOLOU	
LOOZ CU FOL (HTE)	LOI	TOP SIGNAL	77
3.35 ML PP 1078 RC69			4
0.5 0Z Cu HVLP2	minin	GROUND	22
2.99 ML CORE 1x1078		DOWED	4
LOUZ CU HVLP2	minin	FOWER	
3.0ML PP1078R069	1 01	CROUND	4
2.99 ML CORE 1x1078	minin		
0.50Z Cu HVLP2	L05	SIGNAL 1	9
2.93 ML PP 1078 R069			
0.5 0Z Cu HVLP2	L06	GROUND	"
2.99 ML CORE 1x1078			
0.50Z Cu HVLP2	L07	SIGNAL 2	
2.93 ML PP 1078 RC69			
0.5 0Z Cu HVLP2	108	GROUND	
2.99 ML CORE 1x1078			
0.50Z Cu HVLP2	LOY	SIGNAL 3	72
2.93 ML PP1078 H069			4
0.502 CU HVLP2	1111	GROUND	72
2.99 ML CONE 1x10/8	1 11	SICNAL A	
2.81ML PP1078RC69	innn.		
LOOZ CU HVLP2	1 12	GROUND	1
2.99 ML CORE 1x1078			
2.00Z Cu RTF	L13	POWER	
4.99 ML 2XPP 1080 RC55			104 MIL BML
2.0 0Z Cu RTF	L14	POWER	
2.99 ML CORE tx1078			
LOOZ Cu HVLP2	L15	GROUND	
2.8IML PP1078R069			
2004 008 1078		SIGNALO	
2.55ML CORE (KU76	117	CROLIND	
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0.50Z Cu HVLP2	1 18	SIGNAL 6	
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0.50Z Cu HVLP2	L19	GROUND	
2.93 ML PP 1078 R069		W/////////////////////////////////////	
0.5 0Z Cu HVLP2	L20	SIGNAL 7	
2.99 ML CORE 1×1078			
0.5 0Z Cu HVLP2	121	GROUND	
2.93 ML PP 1078 RC69			
0.5 0Z Cu HVLP2	minim	SIGNAL 8	
ZING ML CORE 1x1078		CPOLIND	
0.502 Cu HVLP2	minin		
1007 Cu HVL P2	124	POWER	1
2.99 ML CORE 1x1078	minin	antintationananana eo eo eo eo	
0.50Z Cu HVLP2	L25	GROUND	1
3.35 ML PP 1078 RC69			
100Z Cu FOL (HTE)	L26	BOTTOM SIGNAL	
SILKSCREEN SOLDERMASK			





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# PCB Design Methodology



High-speed, high-power and high-density board

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- Too many rule of thumbs
  - Sometimes conflicting each other
  - Impossible to follow all of them
- Compatibility to standards
  - Maximize margins
- Help understand and debug
- Goal
  - Reducing the number of board iterations
    - Dream first time pass

#### • How

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- Simulation integrated into design flow
  - Iterative processes
- Validation of simulation
  - Integrated PCB test coupon
  - Special test launch points







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 https://iopscience.iop.org/article/10.1088/1748-0221/19/02/C02049/pdf

 Xilinx Crosstalk

Requirement for CEI-28G-VSR

– Rx-Rx

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- <-40dB
- GCM Rx-Rx
  - Majority
    - <-42dB
  - But one
    - ~32dB
  - Optimization
    - Swapping routing layers









#### Before optimization

#### After optimization





### Link Test Results - 25.7 Gb/s NRZ

- All optical links error free with good margin
  - BER < 1E-15







• 8 on-board electric GTM links between MUX and GEP

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- 4 Tx from MUX to GEP
- 4 Tx from GEP to MUX

Name	TX	RX	Status	Bits	Errors	BER	BERT Reset	TX Pattern		RX Pattern		TXUSERCLK Freq	RXUSERCLK Freq	Inject Error	TX Reset	RX Reset	RX PLL Status	TX PLL Status	Loopback Mode		TX Main-Cursor	
😑 Ungrouped Links (0)																						
S Link Group 0 (8)							Reset	PRBS 31	~	PRBS 31	~			Inject	Reset	Reset			None	~	User Design	~
% Link 0	IBERT_5.Quad_118.CH_0.TX	KIBERT_7.Quad_204.CH_0.R	X 60.891 Gbps	3.238E13	0E0	3.088E-14	Reset	PRBS 31	~	PRBS 31	×	380.566	380.566	Inject	Reset	Reset	Locked	Locked	None	~	User Design	×
% Link 1	IBERT_5.Quad_118 CH_1.T)	X IBERT_7.Quad_204.CH_1.R	X 60.891 Gbps	3.238E13	0E0	3.088E-14	Reset	PRBS 31	¥	PRBS 31	×	380.493	380.566	Inject	Reset	Reset	Locked	Locked	None	~	User Design	~
% Link 2	IBERT_5.Quad_118.CH_2.T/	KIBERT_7.Quad_204.CH_2.R	X 60.891 Gbps	3.236E13	0E0	3.09E-14	Reset	PRBS 31	~	PRBS 31	~	380.566	380.493	Inject	Reset	Reset	Locked	Locked	None	~	User Design	~
% Link 3	IBERT_5.Quad_118.CH_3.T/	KIBERT_7.Quad_204.CH_3.R	X 60.879 Gbps	3.233E13	0E0	3.093E-14	Reset	PRBS 31	4	PRBS 31	~	380.493	380.566	Inject	Reset	Reset	Locked	Locked	None	~	User Design	~
% Link 4	IBERT_7.Quad_204.CH_0.TX	KIBERT_5.Quad_118.CH_0.R	X 60.891 Gbps	3.232E13	0E0	3.094E-14	Reset	PRBS 31	~	PRBS 31	×	380.566	380.566	Inject	Reset	Reset	Locked	Locked	None	×	User Design	×
% Link 5	IBERT_7.Quad_204.CH_1.TX	KIBERT_5.Quad_118.CH_1.R	X 60.891 Gbps	3.232E13	0E0	3.094E-14	Reset	PRBS 31	~	PRBS 31	~	380.566	380.566	Inject	Reset	Reset	Locked	Locked	None	~	User Design	~
N Link 6	IBERT_7.Quad_204.CH_2.TX	KIBERT_5.Quad_118.CH_2.R	X 60.891 Gbps	3.231E13	0E0	3.095E-14	Reset	PRBS 31	~	PRBS 31	v	380.566	380.566	Inject	Reset	Reset	Locked	Locked	None	~	User Design	~
% Link 7	IBERT_7.Quad_204.CH_3.T/	KIBERT_5.Quad_118.CH_3.R	X 60.879 Gbps	3.23E13	0E0	3.096E-14	Reset	PRBS 31	~	PRBS 31	~	380.566	380.556	Inject	Reset	Reset	Locked	Locked	None	~	User Design	~



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# Power/Thermal stress test

- Worst Case scenario
  - Both FPGA firmware resource usage 70% + 22 GTM Quads

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- ATCA Fan Level 10
- Total power: 402W
  - MUX 152 W
  - GEP 144 W
- Temperature:
  - MUX 77 °C
  - GEP 65 °C
  - All Firefly modules below 50 °C
  - All power modules < 55 °C</li>
  - Inlet airflow on board 32 °C
  - Outlet airflow on board 46 °C





### Next step



- Slice test with 5 GCMv3 modules at CERN
  - To demonstrate the data flow through the slice (10%) system





### Summary



- ATLAS TDAQ phase-II upgrade will be installed during the LHC LS3 in preparation for the High-Luminosity LHC era.
- The new Global Trigger is the core of the real-time L0 trigger of ATLAS TDAQ phase-II upgrade.
- The Global Trigger is based on FPGA farm of three layers.
  - MUX, GEP and gCTPi
- A full function Global Common Module prototype has been developed to support the functionalities of all nodes in all three layers with different firmware loads.
- GCM is a state-of-the-art high-speed high-density high-power ATCA board designed with a systematic methodology.
- 5 GCM prototype modules have been made and achieved first time pass successfully.





## Backup



### VP1802 GT mapping

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Multipleser					Global	Event Processor			gCTP4								
-	100 -	Para .	to real state	- tes		-		Para .	IS SAFT SAFT IS	PHONE D	ï	Contract State	and and	5 100 Date	an and	5 LAP	
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		CTM (peak 200		onione giorige				GN boat	New York New York New York New York	STATES.			STM Real		ETHOM Sherote		
	2222	arti Gual 286		Constitute		SLR	11111	Chi Suni 200			SLR	CI III	STM Barel 308		ATNONE Visual VIX		
	111111	20 CTYQue 20 CTYQue	100 825 100 825 100 807 100 807	Gast (III	-		222232	III Coal		Barri 93			arcast arcast	11111 Funos	Gard 100	2	





### Optical fibre full mesh exchange



A 60 MUX nodes to 60 GEP nodes full mesh optical fibre exchange can be constructed from above COTS product easily.





Global firmware MUX/gCTPi

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### Global firmware GEP framework

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# Algorithms on Global Trigger

- Combine FEX TOB seeds with full calorimeter cell information above 2  $\sigma$  noise cut
  - Full calorimeter event-based
    - jets using topoclusters, finer calibration and a closer approximation to anti-k\_T jets
    - jet substructure, E\_T and E\_T^miss
  - RoI-based
    - $e/\gamma$  using strips and finer granularity to calculate shower shape  $E_ratio$  or BDT
    - Tau using strips and topoclusters
    - wide area around electron and tau for background for isolation (eFEX 0.3×0.3 in  $\eta \times \phi$ )





### Global GEP firmware floor plan

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# Global firmware management



- Release Management and Continuous Integration based on <u>HoG</u>
  - Guarantees reproducibility and traceability (even locally!)
    - Continuous Integration with minimal additional effort
    - multiple Release branches plus develop branch

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- automatic checking of software and firmware register maps
  - version and SHA cross-checked and written in XMLs and firmware
  - critical for achieving reliability in complex system!



https://hog.readthedocs.io/en/latest/#

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